

**NO FIXTURE METHOD TO CURE DIE ATTACH
FOR BONDING IC DIES TO SUBSTRATES****ABSTRACT**

A no fixture method to cure die attach for bonding IC dies (16) to substrates in which a solvent is applied to top and bottom surfaces of a thermoplastic die attach film (14), prior to component placement of the die (16) on a lead frame die support pad or on a printed circuit board PCB (12). The die attach film (14) is bonded to the IC die (16) and the lead frame, or to the IC die (16) and the printed circuit board PCB (12) upon drying of the solvent.

This Sheet Has Been Replaced

